

General Description

The ESD3Z5.0C is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium.

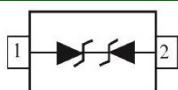
Package outline



Features

- IEC61000-4-2 Level 4 ESD protection
- IEC61000-4-4 Level 4 EFT Protection
- ESD Rating of Class 3(>16kV) per Human Body Model
- 200 Watts Peak Pulse Power per (tp=8/20us)
- Low clamping voltage
- Low leakage current
- Response Time is Typically <1ns

Pin Configuration



Mechanical Data

- SOD-323 Package
- Flammability Rating: UL 94V-0
- High temperature soldering guaranteed: 260°C/10s

ABSOLUTE MACIMUM RATING

Parameters	Symbol	Value	Unit
ESD per IEC61000-4-2(Air)	V _{ESD}	±15	kV
ESD per IEC61000-4-2(Contact)		±8	
Electrostatic Discharge		5	A
ESD Voltage		16	kV
Per Human Body Model		400	V
Per Machine Model			
Total Power Dissipation on FR-5 Board (note 1)@Ta=25°C	P _{PP}	200	W
Maximum Junction temperature	T _J	150	°C
Operating Temperature	T _{OPT}	-40+150	°C
Storage Temperature Range	T _{STG}	-55+150	°C
Lead Soldering Temperature-Maximum (10 second Duration)	T _L	260(10 sec.)	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

Symbol	Parameter	
I _{PP}	Maximum Reverse Peak Pulse Current	
V _c	Clamping Voltage @ I _{pp}	
V _{RWM}	Working Peak Reverse Voltage	
I _R	Maximum Reverse Leakage Current @ V _{RWM}	
V _{BR}	Breakdown Voltage@ I _T	
I _T	Test Current	

Electrical Characteristics (Ta= 25°C unless otherwise noted, VF=0.9V Max.@ IF=10mA for all types).

DEVICE	MARKING	VRWM	IR(uA)	VBR(V)		IT (mA)	Vc@IPP=5A (V)	Vc(V)(Note1) @Max IPP	IPP(A) (Note1)	Ppk (W)	C (pF)
		(V)	@VRWM	Max	Min						
ESD3Z5.0C	3M	5.0	1.0	5.6	7.8	1.0	11.6	18.6	9.4	174	25

Note: 1. Surge current waveform per Figure 1.

2. VBR is measured with a pulse test current IT at an ambient temperature of 25°C

ELECTRICAL CHARACTERISTICS CURVES

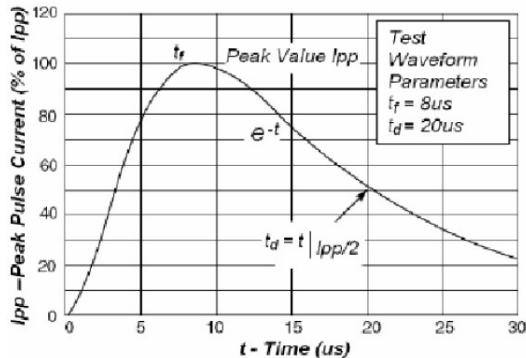


Fig1. Pulse Waveform

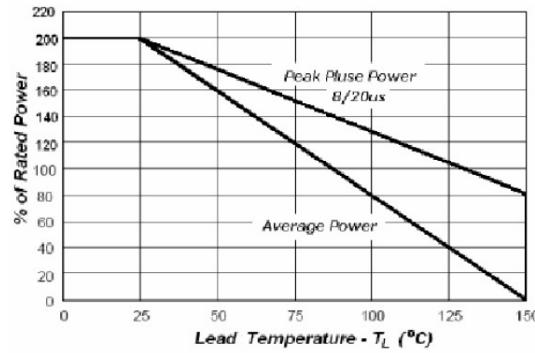
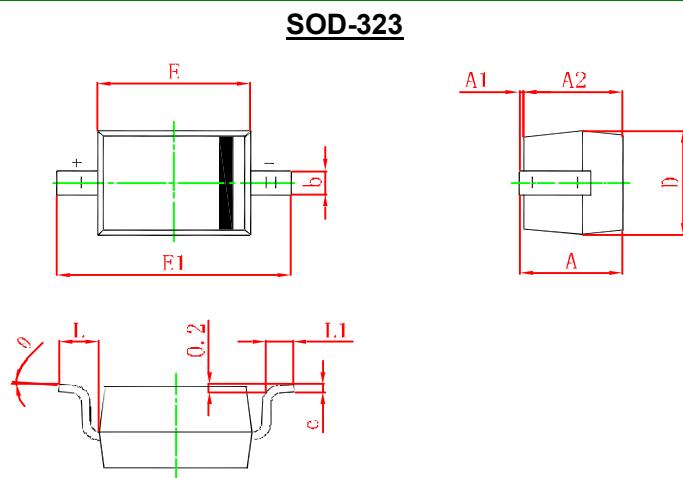


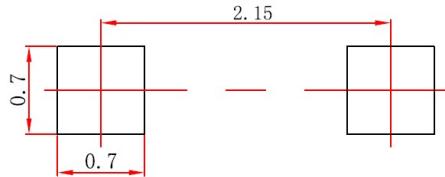
Fig2. Power Derating

SOD-323 PACKAGE OUTLINE Plastic surface mounted package



Symbol	Min.(mm)	Max.(mm)
A		1.000
A1	0.000	0.100
A2	0.800	0.900
b	0.250	0.350
c	0.080	0.150
D	1.200	1.400
E	1.600	1.800
E1	2.500	2.700
L	0.475REF	
L1	0.250	0.400
θ	0°	8°

SOD-323 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.